

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Scott E. Moore, Whonchee Lee, Scott G. Meikle and Trung T. Doan

Filed : March 4, 2002

For : METHODS AND APPARATUS FOR ELECTROCHEMICAL-MECHANICAL PROCESSING OF MICROELECTRONIC WORKPIECES

Docket No. : 108298544US

Date : March 4, 2002

Box Patent Application
Commissioner for Patents
Washington, DC 20231

PRELIMINARY AMENDMENT

Dear Commissioner:

In keeping with 37 C.F.R. § 1.121(b) and (c), this paper includes a clean version of the amended specification paragraph upon entry of this amendment. An appendix is attached showing the marked-up version of the specification paragraph amended in this amendment. Please amend the application as follows and reconsider the application in light of the following remarks.

In the Specification:

Please amend the following specification paragraph:


CROSS-REFERENCE TO RELATED APPLICATION(S)

[0001] The present application is a continuation-in-part of U.S. Application No. 09/651,779, filed August 30, 2000 and entitled "Methods and Apparatus for Removing Conductive Material from a Microelectronic Substrate;" U.S. Application No. 09/888,084, filed June 21, 2001, and entitled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material from a Microelectronic Substrate;" and U.S. Application No. 09/887,767, filed June 21, 2001, and entitled "Microelectronic Substrate Having Conductive Material With Blunt-Cornered Apparatus, and Associated Methods for Removing Conductive Material;" all of which are herein incorporated in their entirety by reference.

REMARKS

Applicants respectfully request consideration of the application in view of this preliminary amendment. If the Examiner has any questions or matters that can be expediently handled by telephone, he or she is encouraged to contact Mr. Parker, attorney for the Applicants.

Respectfully submitted,
Perkins Coie LLP



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Appendix – Specification

Marked to Show Changes

CROSS-REFERENCE TO RELATED APPLICATION(S)

[0001] The present application is a continuation-in-part of U.S. Application No. 09/651,797, filed August 30, 2000 and entitled "Methods and Apparatus for Removing Conductive Material from a Microelectronic Substrate;" U.S. Application No. 09/888,084, filed June 21, 2001, and entitled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material from a Microelectronic Substrate;" and U.S. Application No. 09/887,767, filed June 21, 2001, and entitled "Microelectronic Substrate Having Conductive Material With Blunt-Cornered Apparatus, and Associated Methods for Removing Conductive Material;" all of which are herein incorporated in their entirety by reference.